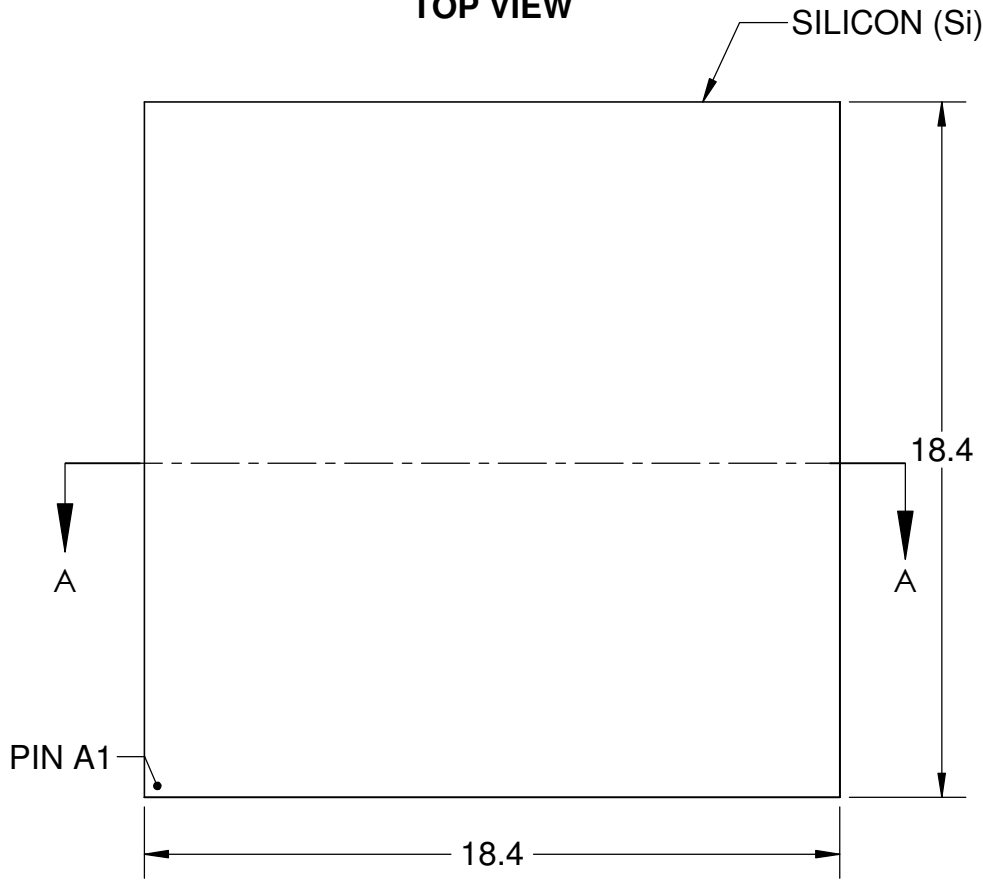
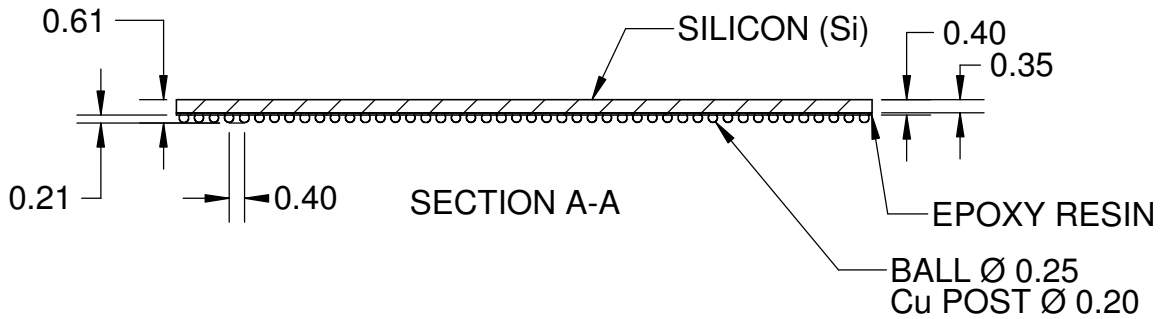
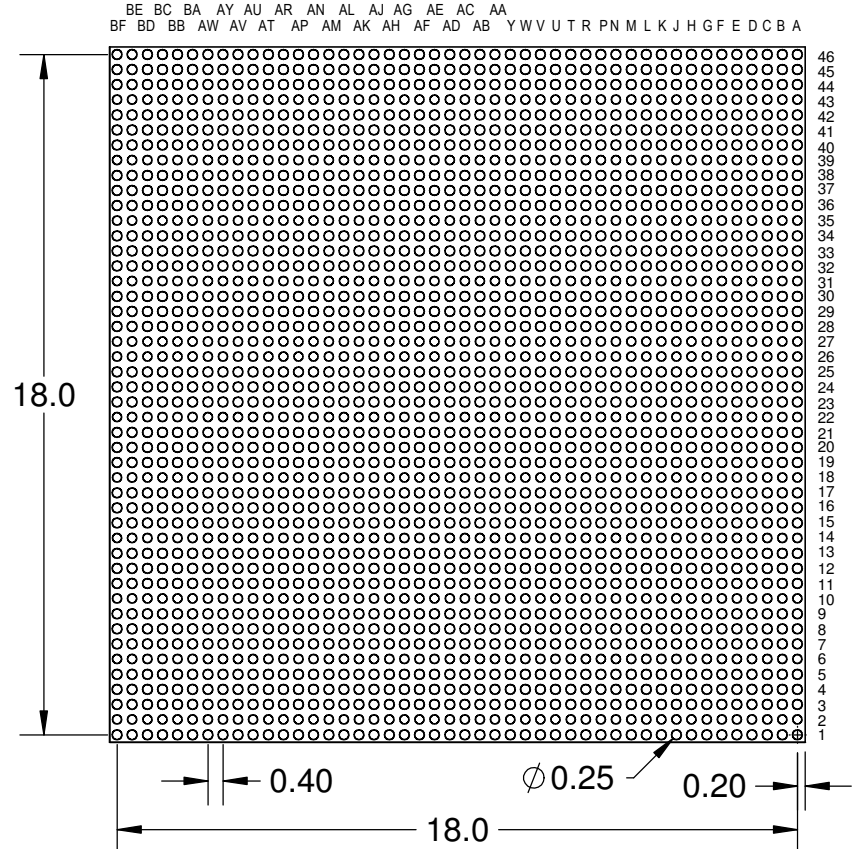


**TOP VIEW**



**BALL VIEW**



- Notes: (Unless Otherwise Specified).  
 1) ALL DIMENSIONS ARE IN MM.  
 2) SOLDER BALL ALLOY:  
 STANDARD: SAC305 (Sn96.5/Ag3.0/Cu0.5).  
 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm.  
 4) NON-SOLDER MASK DEFINED PAD.  
 5) PAD Cu DIAMETER: 0.20mm.  
 6) SUBSTRATE MATERIAL: Si (SILICON).  
 7) DAISY CHAIN PATTERN (SEE PAGE 2).

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP2116T.4C-DC476D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES

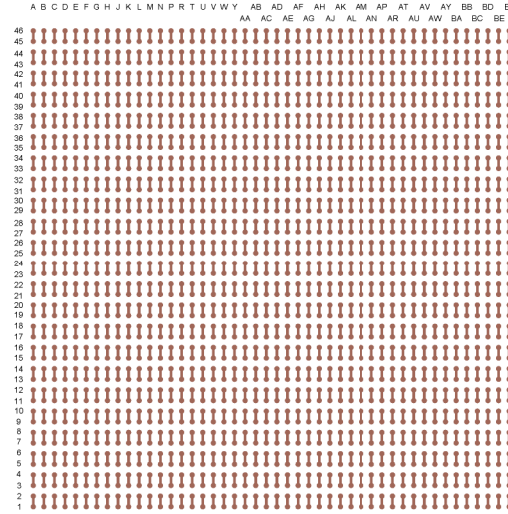
APPROVALS	DATE	<b>TopLine®</b>			
DRAWN T. Au	02/06/18				
ENG M. Hart	02/06/18	TITLE	WLP2116T.4C-DC467D 2116 BALL P=0.4mm		
MFG		SCALE	SIZE	DRAWING NO.	REV
QA			A	544670	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 2
REVISED					

# DAISY CHAIN PATTERN

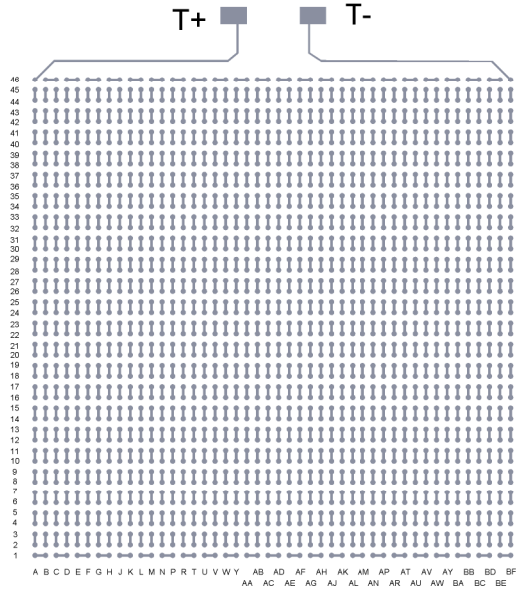
BALL VIEW



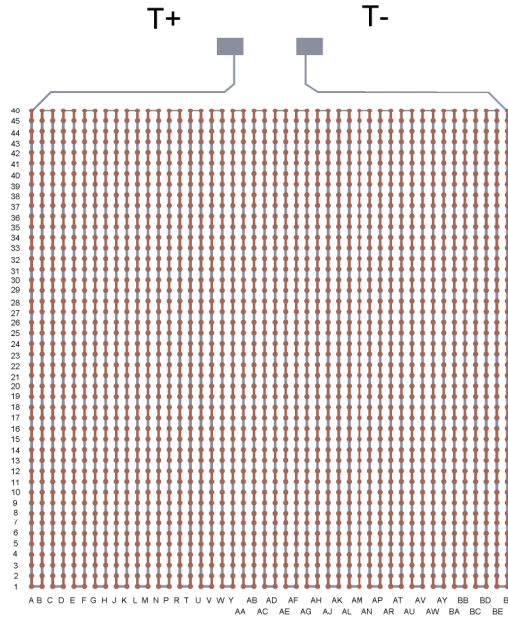
BOTTOM SIDE  
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING  
TO TEST BOARD  
(TOP X-RAY VIEW)



**Notes:**

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.20mm (7.9mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.10mm (3.9mil).

<b>TopLine®</b>			
TITLE		WLP2116T.4C-DC467D 2116 BALL P=0.4mm	
SCALE	SIZE	DRAWING NO.	REV
	A	544670	A
DO NOT SCALE DRAWING			SHEET 2 OF 2